

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	((("5589029") or ("6201306"))).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/21 10:12
S2	5	("5589029").URPN.	USPAT	OR	ON	2004/12/20 12:38
S3	8	("4667402" "4859269" "4874444" "4990051" "5169196" "5351872" "5447266" "5589029").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/20 12:40
S4	13	("4990051").URPN.	USPAT	OR	ON	2004/12/20 12:44
S5	3921	semiconductor adj die and adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 12:45
S6	13	joules and S5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 12:44
S7	71	semiconductor adj die and adhesive adj strength	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 13:47
S8	2	"11207532"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 13:48
S9	2	"2000277986"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 13:48
S10	514	ejector adj pin and (blow or blowing or forced adj air)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 10:13
S11	225	die and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 10:13

S12	99	(tape or film or adhesive) and S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 10:15
S13	2	semiconductor adj die and S12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 10:19
S14	2	semiconductor adj die and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 10:20
S15	5	(peel or delaminate) and (forced adj air or blowing) and semiconductor adj die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 10:35
S16	3	("6505397").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/21 10:35